

# ULTRALOW-NOISE, HIGH PSRR, FAST RF 100-mA LOW-DROPOUT LINEAR REGULATORS

### FEATURES

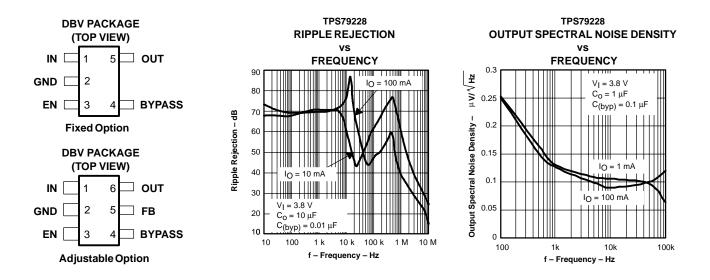
- 100-mA Low-Dropout Regulator With EN
- Available in 2.5-V, 2.8-V, 3-V, and Adj.
- High PSRR (75 dB at 10 kHz)
- Ultralow Noise (27 μV)
- Fast Start-Up Time (50 μs)
- Stable With Any 1-µF Ceramic Capacitor
- Excellent Load/Line Transient
- Very Low Dropout Voltage (55 mV at Full Load, TPS79230)
- 5-Pin SOT23 (DBV) Package
- TPS791xx Provides EN Options

## **APPLICATIONS**

- Cellular and Cordless Telephones
- VCOs
- RF
- Bluetooth<sup>™</sup>, Wireless LAN
- Handheld Organizers, PDA

## DESCRIPTION

The TPS792xx family of low-dropout (LDO) low-power linear voltage regulators features high power supply rejection ratio (PSRR), ultralow noise, fast start-up, and excellent line and load transient responses in a small outline, SOT23, package. Each device in the family is stable, with a small 1-µF ceramic capacitor on the output. The family uses an advanced, proprietary BiCMOS fabrication process to yield extremely low dropout voltages (e.g., 55 mV at 100 mA, TPS79230). Each device achieves fast start-up times (approximately 50  $\mu$ s with a 0.001  $\mu$ F bypass capacitor) while consuming very low guiescent current (170 µA typical). Moreover, when the device is placed in standby mode, the supply current is reduced to less than 1  $\mu$ A. The TPS79228 exhibits approximately 27  $\mu$ V<sub>RMS</sub> of output voltage noise with a 0.1 µF bypass capacitor. Applications with analog components that are noise sensitive, such as portable RF electronics, benefit from the high PSRR and low noise features as well as the fast response time.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Bluetooth is a trademark owned by the Bluetooth SIG, Inc.



SLVS337B - MARCH 2001 - REVISED MAY 2002



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

#### ORDERING INFORMATION

Tj	VOLTAGE	PACKAGE	PART N	SYMBOL	
	1.2 to 5.5 V		TPS79201DBVT(1)	TPS79201DBVR(2)	PEVI
–40°C to 125°C	2.5 V	2.5 V SOT23	TPS79225DBVT(1)	TPS79225DBVR(2)	PEXI
	2.8 V (DBV)	TPS79228DBVT(1)	TPS79228DBVR <sup>(2)</sup>	PEWI	
	3 V		TPS79230DBVT(1)	TPS79230DBVR <sup>(2)</sup>	PEYI

(1) The DBVT indicates tape and reel of 250 parts.

(2) The DBVR indicates tape and reel of 3000 parts.

### **ABSOLUTE MAXIMUM RATINGS**

over operating free-air temperature range (unless otherwise noted)(1)

	TPS79201,TPS79225 TPS79228,TPS79230
Input voltage range (2)	-0.3 V to 6 V
Voltage range at EN	–0.3 V to V <sub>I</sub> + 0.3 V
Voltage on OUT	-0.3 V to 6 V
Peak output current	Internallylimited
ESD rating, HBM	2 kV
ESD rating, CDM	500 V
Continuous total power dissipation	See Dissipation Rating Table
Operating virtual junction temperature range, TJ	−40°C to 150°C
Operating ambient temperature range, T <sub>A</sub>	-40°C to 85°C
Storage temperature range, T <sub>Stg</sub>	−65°C to 150°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values are with respect to network ground terminal.

### PACKAGE DISSIPATION RATING

BOARD	PACKAGE	$R_{\theta}$ JC	$R_{\theta JA}$	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	$T_A \le 25^{\circ}C$ POWER RATING	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING
Low K(1)	DBV	63.75°C/W	256°C/W	3.906 mW/°C	391 mW	215 mW	156 mW
High K(2)	DBV	63.75°C/W	178.3°C/W	5.609 mW/°C	561 mW	308 mW	224 mW

(1) The JEDEC low K (1s) board design used to derive this data was a 3-inch x 3-inch, two layer board with 2 ounce copper traces on top of the board. (2) The JEDEC high K (2s2p) board design used to derive this data was a 3-inch x 3-inch, multilayer board with 1 ounce internal power and ground

planes and 2 ounce copper traces on top and bottom of the board.

### **RECOMMENDED OPERATING CONDITIONS**

	MIN	NOM M	AX	UNIT
Input voltage, VI (1)	2.7		5.5	V
Continuous output current, I <sub>O</sub> <sup>(2)</sup>	0		00	mA
Operating junction temperature, TJ	-40		25	°C

(1) To calculate the minimum input voltage for your maximum output current, use the following formula:

 $V_{I}(min) = V_{O}(max) + V_{DO}(max load)$ 

(2) Continuous output current and operating junction temperature are limited by internal protection circuitry, but it is not recommended that the device operate under conditions beyond those specified in this table for extended periods of time.

SLVS337B-MARCH 2001 - REVISED MAY 2002

### ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range, (T<sub>J</sub> = -40 to 125°C), V<sub>I</sub> = V<sub>O(typ)</sub> + 1 V, I<sub>O</sub> = 1 mA, EN = V<sub>I</sub>, C<sub>O</sub> = 10  $\mu$ F, C<sub>(byp)</sub> = 0.01  $\mu$ F (unless otherwise noted)

PARAMETER		TEST CON	MIN	TYP	MAX	UNIT			
	TD070004	T <sub>J</sub> = 25°C,	$1.22 \text{ V} \le \text{V}_{O} \le 5.2$		VO				
	TPS79201	0 μA < I <sub>O</sub> < 100 mA,	1.22 V ≤ V <sub>O</sub> ≤ 5.2 V (1)	0.98 V <sub>O</sub>		1.02 V <sub>O</sub>	v		
	TD070005	T <sub>J</sub> = 25°C			2.5				
Outputs when a	TPS79225	$0 \mu\text{A} < \text{I}_{O} < 100 \text{mA},$	3.5 V < Vj < 5.5 V	2.45		2.55			
Output voltage	TPS79228	T <sub>J</sub> = 25°C			2.8		v		
	195/9226	$0 \ \mu A < I_O < 100 \ mA$ ,	3.8 V < VI < 5.5 V	2.744		2.856			
	TPS79230	Tj = 25°C			3				
	1579230	$0 \ \mu A < I_O < 100 \ mA$ ,	4 V < Vj < 5.5 V	2.94		3.06			
Quiescent current (GND current)		$0 \ \mu A < I_O < 100 \ mA$ ,	$T_J = 25^{\circ}C$		170				
Quescent current (GND current)		$0 \mu A < I_O < 100 mA$				250	μA		
Loadregulation		$0 \ \mu A < I_O < 100 \ mA$ ,	$T_J = 25^{\circ}C$		5		mV		
Output voltage line regulation ( $\Delta$ )	(a)(2)	$V_{O}$ + 1 V < $V_{I} \le 5.5$ V,	$T_J = 25^{\circ}C$		0.05				
Output voltage line regulation (20	0/00/-/	$V_{O} + 1 V < V_{I} \le 5.5 V,$				0.12	/0/ V		
			$C_{(byp)} = 0.001  \mu F$		50		μVRMS		
Output noise voltage (TPS79228	Ň	BW = 100 Hz to 100 kHz,	$C_{(byp)} = 0.0047 \mu F$		33				
Output holse voltage (1F 37 9220)	)	$I_{O} = 100 \text{ mA}, T_{J} = 25^{\circ}C$	$C_{(byp)} = 0.01  \mu F$		31				
			$C_{(byp)} = 0.1  \mu F$		27				
			$C_{(byp)} = 0.001  \mu F$		50				
Time, start-up (TPS79228)		$R_L = 28 \Omega$ , $C_O = 1 \mu$ F, T <sub>1</sub> = 25°C	$C_{(byp)} = 0.0047  \mu F$		70		μs		
		5	C <sub>(byp)</sub> = 0.01 μF		90				
Output current limit		$V_{O} = 0 \vee (1)$	285		600	mA			
UVLO threshold		V <sub>CC</sub> rising	2.25		2.65	V			
UVLO hysteresis		TJ = 25°C		100		mV			
Standby current		EN = 0 V, 2.7 V < V <sub>I</sub> < 5.5 V			0.7	1	μA		
High level enable input voltage		2.7 V < V <sub>I</sub> < 5.5 V		2			V		
Low level enable input voltage		2.7 V < Vj < 5.5 V			0.7	V			
Input current (EN)		EN = 0 V		-1		1	μA		
		f = 100 Hz, T <sub>J</sub> = 25°C,	l <sub>O</sub> = 10 mA		70				
Device over the size loss of the s	TDCZ0000	f = 100 Hz, T <sub>J</sub> = 25°C,		72					
Power supply ripple rejection	TPS79228	$f = 10 \text{ kHz}, T_J = 25^{\circ}\text{C}, I_O = 100 \text{ mA}$		75		dB			
		f = 100 kHz, T <sub>J</sub> = 25°C,	l <sub>O</sub> = 100 mA		47		1		
	TDOZOGOG	I <sub>O</sub> = 100 mA,	TJ = 25°C		60				
D ( ) (2)	TPS79228	I <sub>O</sub> = 100 mA	_			110	mV		
Dropout voltag(3)		I <sub>O</sub> = 100 mA,	Tj = 25°C		55				
	TPS79230	I <sub>O</sub> = 100 mA				100			

(1) The minimum IN operating voltage is 2.7 V or V<sub>O(typ)</sub> + 1 V, whichever is greater. The maximum IN voltage is 5.5 V. The maximum output current is 100 mA.

(2) If  $V_0 \le 2.5$  V then  $V_{Imin} = 2.7$  V,  $V_{Imax} = 5.5$  V:

Line regulation (mV) = 
$$(\%/V) \times \frac{V_O(V_{Imax} - 2.7 V)}{100} \times 1000$$

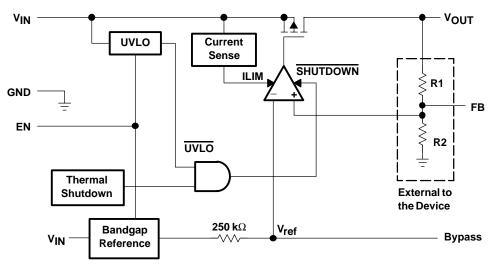
If V<sub>O</sub>  $\ge$  2.5 V then V<sub>Imin</sub> = V<sub>O</sub> + 1 V, V<sub>Imax</sub> = 5.5 V:

 $^{(3)}$  IN voltage equals V<sub>O</sub>(typ) – 100 mV; The TPS79225 dropout voltage is limited by the input voltage range limitations.

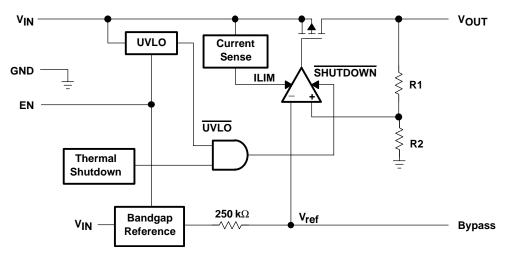


SLVS337B - MARCH 2001 - REVISED MAY 2002

#### FUNCTIONAL BLOCK DIAGRAM—ADJUSTABLE VERSION



#### FUNCTIONAL BLOCK DIAGRAM—FIXED VERSION



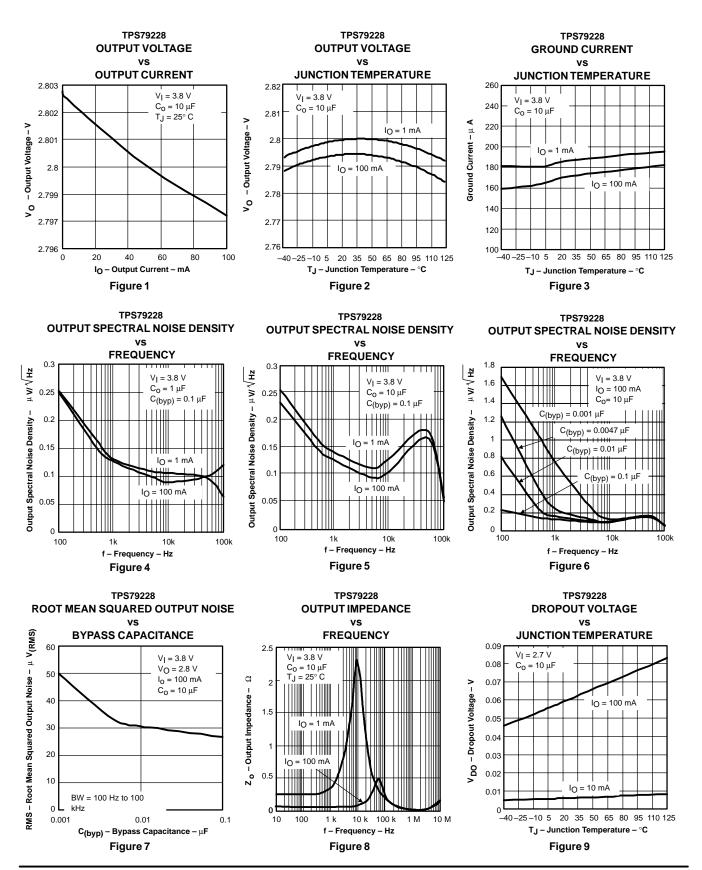
#### **Terminal Functions**

TE	RMINAL	-		DECODIDENCI
NAME	ADJ	FIXED	1/0	DESCRIPTION
BYPASS	4	4		An external bypass capacitor, connected to this terminal, in conjunction with an internal resistor, creates a low-pass filter to further reduce regulator noise.
EN	3	3	I	The EN terminal is an input which enables or shuts down the device. When EN goes to a logic high, the device will be enabled. When the device goes to a logic low, the device will be in shutdown mode.
FB	5	N/A	I	This terminal is the feedback input voltage for the adjustable device.
GND	2	2		Regulatorground
IN	1	1	I	The IN terminal is the input to the device.
OUT	6	5	0	The OUT terminal is the regulated output of the device.

SLVS337B-MARCH 2001-REVISED MAY 2002

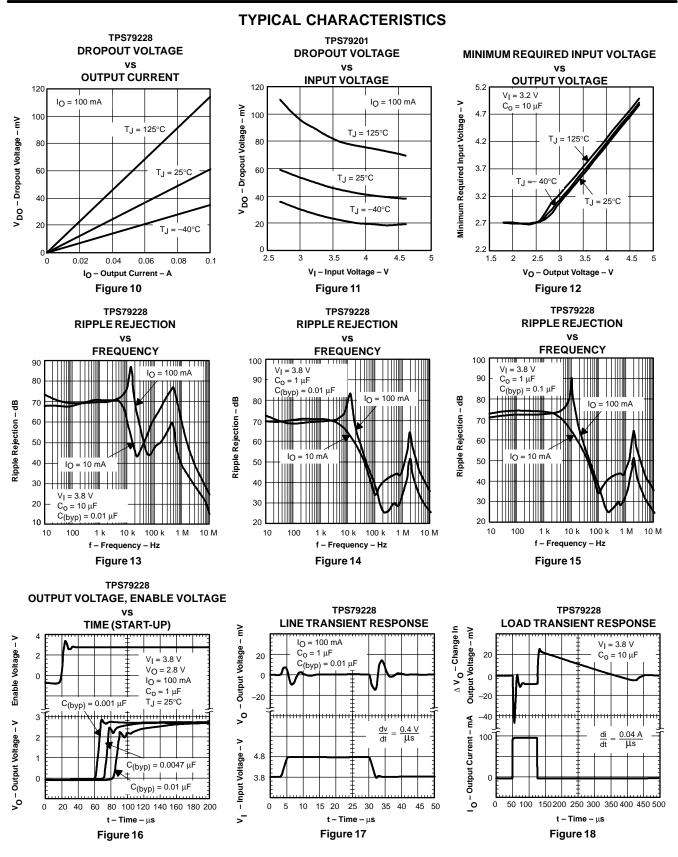
### **TYPICAL CHARACTERISTICS**

TRUMENTS www.ti.com





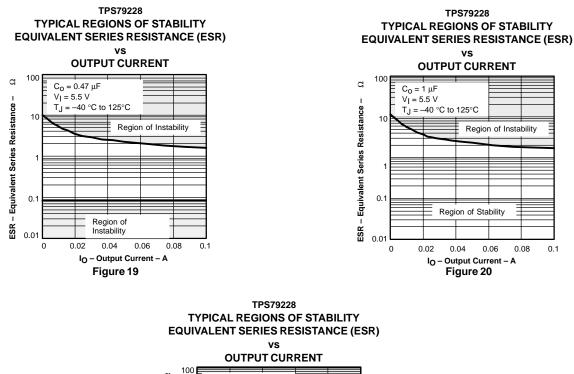
SLVS337B - MARCH 2001 - REVISED MAY 2002

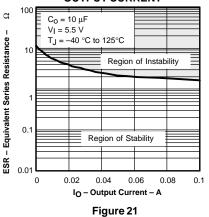


SLVS337B - MARCH 2001 - REVISED MAY 2002

#### **TYPICAL CHARACTERISTICS**

TEXAS TRUMENTS www.ti.com







SLVS337B - MARCH 2001 - REVISED MAY 2002

### **APPLICATION INFORMATION**

The TPS792xx family of low-dropout (LDO) regulators have been optimized for use in noise-sensitive battery-operated equipment. The device features extremely low dropout voltages, high PSRR, ultralow output noise, low quiescent current (170 µA typically), and enable-input to reduce supply currents to less than 1 µA when the regulator is turned off.

A typical application circuit is shown in Figure 22.

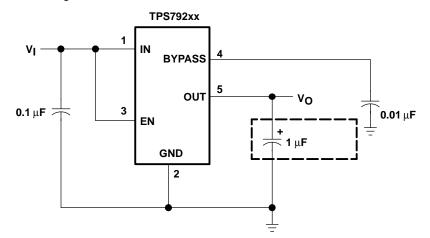


Figure 22. Typical Application Circuit

### **EXTERNAL CAPACITOR REQUIREMENTS**

A 0.1-µF or larger ceramic input bypass capacitor, connected between IN and GND and located close to the TPS792xx, required for stability and to improve transient response, noise rejection, and ripple rejection. A higher-value electrolytic input capacitor may be necessary if large, fast-rise-time load transients are anticipated and the device is located several inches from the power source.

Like all low dropout regulators, the TPS792xx requires an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance is 1  $\mu$ F. Any 1  $\mu$ F or larger ceramic capacitor is suitable. The device is also stable with a 0.47  $\mu$ F ceramic capacitor with at least 75 m $\Omega$  of ESR.

The internal voltage reference is a key source of noise in an LDO regulator. The TPS792xx has a BYPASS pin which is connected to the voltage reference through a 250-k $\Omega$  internal resistor. The 250-k $\Omega$  internal resistor, in conjunction with an external bypass capacitor connected to the BYPASS pin, creates a low pass filter to reduce the voltage reference noise and, therefore, the noise at the regulator output. In order for the regulator to operate properly, the current flow out of the BYPASS pin must be at a minimum because any leakage current creates an IR drop across the internal resistor thus creating an output error. Therefore, the bypass capacitor must have minimal leakage current.

For example, the TPS79228 exhibits only 31  $\mu$ V<sub>RMS</sub> of output voltage noise using a 0.1- $\mu$ F ceramic bypass capacitor and a 1- $\mu$ F ceramic output capacitor. Note that the output starts up slower as the bypass capacitance increases due to the RC time constant at the bypass pin that is created by the internal 250-k $\Omega$  resistor and external capacitor.

### BOARD LAYOUT RECOMMENDATION TO IMPROVE PSRR AND NOISE PERFORMANCE

To improve ac measurements like PSRR, output noise, and transient response, it is recommended that the board be designed with separate ground planes for  $V_{IN}$  and  $V_{OUT}$ , with each ground plane connected only at the ground pin of the device. In addition, the ground connection for the bypass capacitor should connect directly to the ground pin of the device.



### POWER DISSIPATION AND JUNCTION TEMPERATURE

Specified regulator operation is assured to a junction temperature of  $125^{\circ}$ C; the maximum junction temperature should be restricted to  $125^{\circ}$ C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation,  $P_{D(max)}$ , and the actual dissipation,  $P_{D}$ , which must be less than or equal to  $P_{D(max)}$ .

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_{J}max - T_{A}}{R_{\theta JA}}$$
(1)

Where:

T<sub>J</sub>max is the maximum allowable junction temperature.

 $R_{\theta JA}$  is the thermal resistance junction-to-ambient for the package, see the dissipation rating table.

T<sub>A</sub> is the ambient temperature.

The regulator dissipation is calculated using:

$$\mathsf{P}_{\mathsf{D}} = \left(\mathsf{V}_{\mathsf{I}} - \mathsf{V}_{\mathsf{O}}\right) \times \mathsf{I}_{\mathsf{O}} \tag{2}$$

Power dissipation resulting from quiescent current is negligible. Excessive power dissipation triggers the thermal protection circuit.

#### **PROGRAMMING THE TPS79201 ADJUSTABLE LDO REGULATOR**

The output voltage of the TPS79201 adjustable regulator is programmed using an external resistor divider as shown in Figure 23. The output voltage is calculated using:

$$V_{O} = V_{ref} \times \left(1 + \frac{R1}{R2}\right)$$
(3)

Where:

V<sub>ref</sub> = 1.2246 V typ (the internal reference voltage)

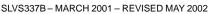
Resistors R1 and R2 should be chosen for approximately  $50-\mu A$  divider current. Lower value resistors can be used for improved noise performance, but the solution consumes more power. Higher resistor values should be avoided as leakage current into/out of FB across R1/R2 creates an offset voltage that artificially increases/decreases the feedback voltage and thus erroneously decreases/increases V<sub>0</sub>. The recommended design procedure is to choose R2 = 30.1 k $\Omega$  to set the divider current at 50  $\mu$ A, C1 = 15 pF for stability, and then calculate R1 using:

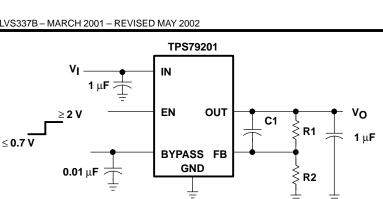
$$R1 = \left(\frac{V_{O}}{V_{ref}} - 1\right) \times R2$$
(4)

In order to improve the stability of the adjustable version, it is suggested that a small compensation capacitor be placed between OUT and FB. For voltages <1.8 V, the value of this capacitor should be 100 pF. For voltages >1.8 V, the approximate value of this capacitor can be calculated as:

$$C1 = \frac{(3 \times 10^{-7}) \times (R1 + R2)}{(R1 \times R2)}$$
(5)

The suggested value of this capacitor for several resistor ratios is shown in the table below. If this capacitor is not used (such as in a unity-gain configuration) or if an output voltage < 1.8 V is chosen, then the minimum recommended output capacitor is 2.2  $\mu$ F instead of 1  $\mu$ F.







#### OUTPUT VOLTAGE **PROGRAMMING GUIDE**

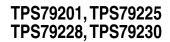
OUTPUT VOLTAGE	R1	R2	C1	
2.5 V	33.4 kΩ	30.1 kΩ	22 pF	
3.3 V	53.6 kΩ	30.1 kΩ	15 pF	
3.6 V	59 kΩ	30.1 kΩ	15 pF	

#### Figure 23. TPS79201 Adjustable LDO Regulator Programming

#### **REGULATOR PROTECTION**

The TPS792xx PMOS-pass transistor has a built-in back diode that conducts reverse current when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. If extended reverse voltage operation is anticipated, external limiting might be appropriate.

The TPS792xx features internal current limiting and thermal protection. During normal operation, the TPS792xx limits output current to approximately 400 mA. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package or the absolute maximum voltage ratings of the device. If the temperature of the device exceeds approximately 165°C, thermal-protection circuitry shuts it down. Once the device has cooled down to below approximately 140°C, regulator operation resumes.

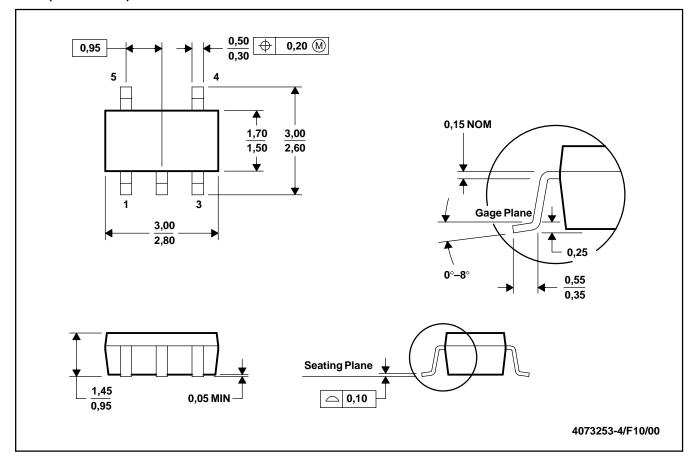


SLVS337B - MARCH 2001 - REVISED MAY 2002



#### **MECHANICAL DATA**

DBV (R-PDSO-G5) PLASTIC SMALL-OUTLINE



NOTES:A. All linear dimensions are in millimeters.

This drawing is subject to change without notice. Body dimensions do not include mold flash or protrusion. В. С.

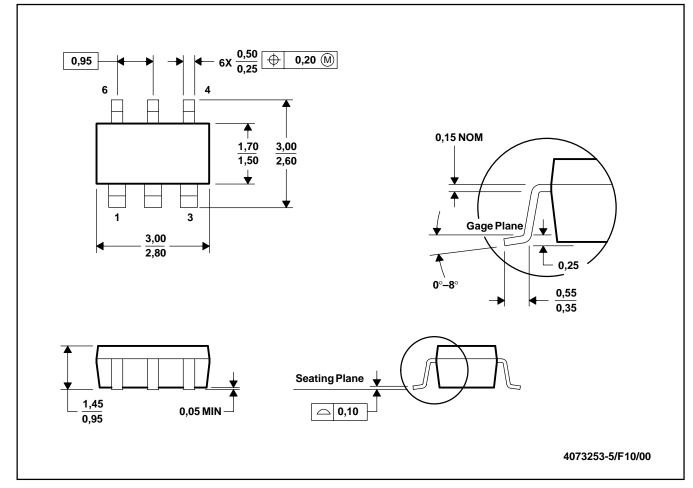
D. Falls within JEDEC MO-178



SLVS337B - MARCH 2001 - REVISED MAY 2002

#### **MECHANICAL DATA**

DBV (R-PDSO-G6) PLASTIC SMALL-OUTLINE



NOTES:A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Leads 1, 2, 3 are wider than leads 4, 5, 6 for package orientation.
- E. Pin 1 is located below the first letter of the top side symbolization.

4-Nov-2005

#### **PACKAGING INFORMATION**

MENTS

www ti com

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	n MSL Peak Temp <sup>(3)</sup>
TPS79201DBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS79201DBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS79201DBVTG4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS79225DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS79225DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS79225DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS79225DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS79228DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS79228DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS79228DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS79228DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS79230DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS79230DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS79230DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS79230DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the

# PACKAGE OPTION ADDENDUM



accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address:

Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated